

## WIRE BONDING SERVICES

Wire bonding is a key manufacturing process for microelectronics and MEMS sensor products. The core wire bonding capabilities and expertise at SMART Microsystems support process development, testing, and manufacturing of sub-assemblies designed by our customers. Wire bonding processes are flexible and robust, allowing our customers to quickly realize a microelectronic package assembly solution for their products. For additional information you can visit our website, or you can call or send us an email to discuss your wire bonding needs.

### FINE GAUGE WIRE/RIBBON BONDING

- Wire diameters: 17.5 $\mu$ m to 50 $\mu$ m (0.7 to 2.0 mil)
- Ribbon: 6x35 $\mu$ m to 25x250 $\mu$ m (0.25x1.4 mil to 1x10 mil)
- Wire and ribbon materials: aluminum, gold
- Fine pitch is available
- Bond area: 305mm x 410mm (12.3" x 16.14")
- Accuracy: 1 $\mu$ m at 3 sigma
- Speed: up to 6 wires/second
- Loop Length: 70  $\mu$ m up to 20 mm, depending on wire diameter
- Various loop form functions:
  - Constant wire length
  - Constant loop height
  - Individual loop shapes

### HEAVY GAUGE WIRE/RIBBON BONDING

- Wire diameters: 100 $\mu$ m to 500 $\mu$ m (4 to 20 mil)
- Ribbon: 0.075x0.75mm to 0.4mm x 2mm (3x30 mil to 16x80 mil)
- Wire and ribbon materials: aluminum, copper
- Bond area: 300mm x 500mm (13.8" x 19.7")
- Accuracy: 2 $\mu$ m at 3 sigma
- Speed: up to 3 wires/sec

### GOLD BALL BONDING

- Wire diameters: 15 to 50 $\mu$ m (0.6 to 2.0 mil)
- Wire materials: gold
- Fine pitch capability: 40 $\mu$ m
- Minimum loop height: 100 $\mu$ m (standard and worked loops)
- Bond area: 56mm x 80mm
- Accuracy: +/- 2.0 $\mu$ m
- Speed: up to 15 bonds/second including programmable looping
- Looping capability: standard and worked (BGA1-BGA3, Spider, J Wire, CSB)
- Stand-off Stitch bond (SSB) capable
- Stud bumping
- Wire material: gold
- Speed: Up to 30 bumps/second including programmable smoothing



*Hesse Mechatronics  
Fine Gauge Wedge Bonder*



*Hesse Mechatronics  
Heavy Gauge Wedge Bonder*



*K&S IConn Gold Ball Bonder*